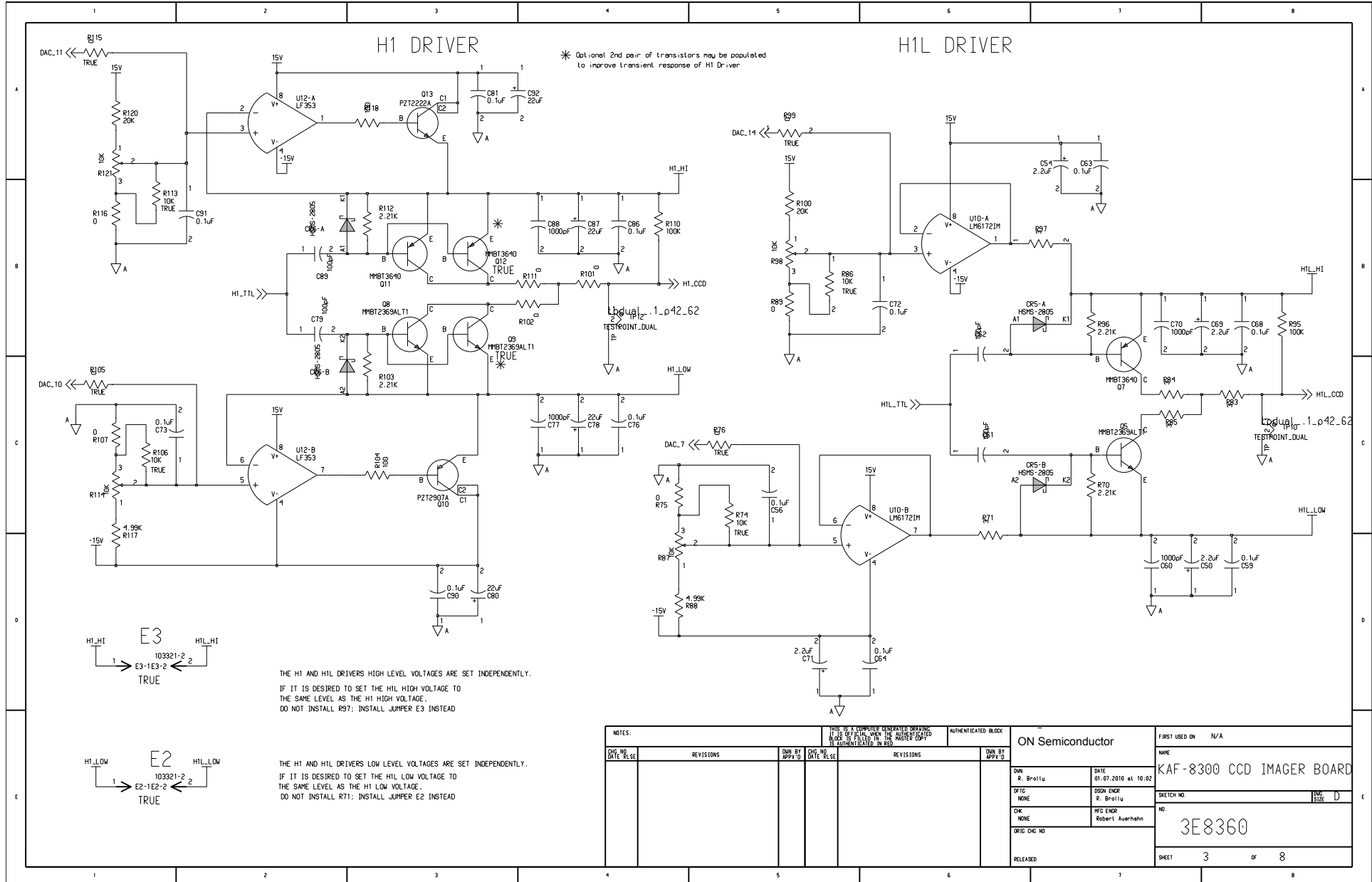


NOTES:		THIS IS A SUPPLIER GENERATED DRAWING. IT IS OF FINAL, WHEN THE AUTHORIZED USER IS FILLED IN. THE MASTER COPY IS AUTHORIZED TO BE RE-USED.		AUTHENTICATED BLOCK	
DATE	REVISE	DATE	REVISE	DATE	REVISE
ON Semiconductor			FIRST USED ON N/A		
NAME			KAF-8300 CCD IMAGER BOARD		
DATE			01.07.2010 at 10:00		
DESIGN ENGR			R. Bröllu		
SKETCH NO.					
DWG ENGR			Robert Auerhahn		
NO.			3E8360		
SHEET			2 OF 8		

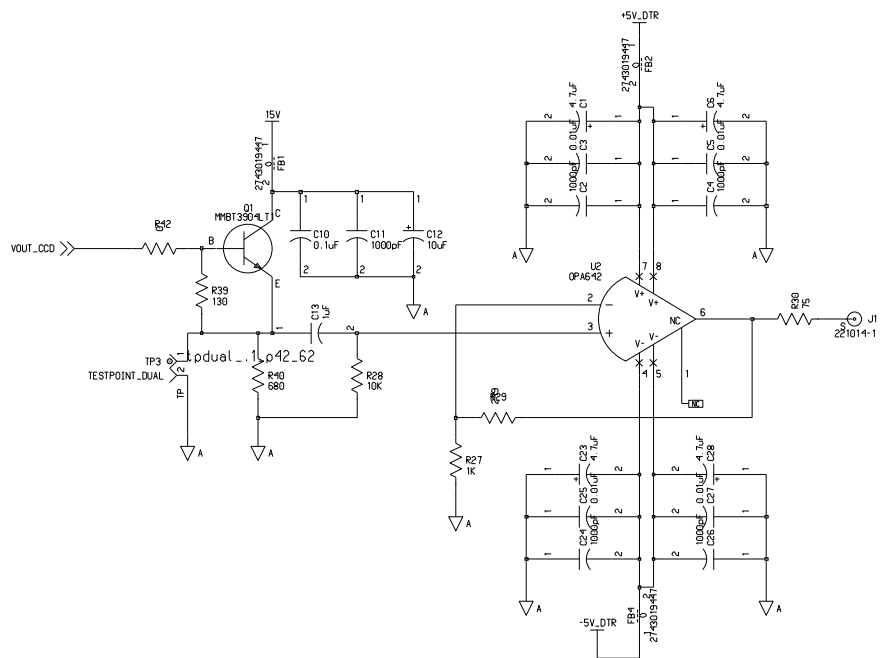


NOTES:			AUTHENTICATED BLOCK		
THIS IS A REGISTERED SERVICE BOUNDING BLOCK. IT IS OF FULL WHEN THE AUTHENTICATED BLOCK IS AUTHENTICATED IN RED.					
DATE	REVISIONS	DESIGNED BY	DATE	REVISIONS	DESIGNED BY
DATE RELEASE		APP'D	DATE RELEASE		APP'D
<b>ON Semiconductor</b>					
DATE: 01.07.2010 at 10:02			NAME: KAF-8300 CCD IMAGER BOARD		
DESIGN ENGR: R. Bröllu			DRAWN: NONE		
MFG ENGR: Robert Auerhahn			SHEET NO: 3		
ORIG. DATE NO:			NO. 3E8360		
RELEASED:			SHEET 3 OF 8		

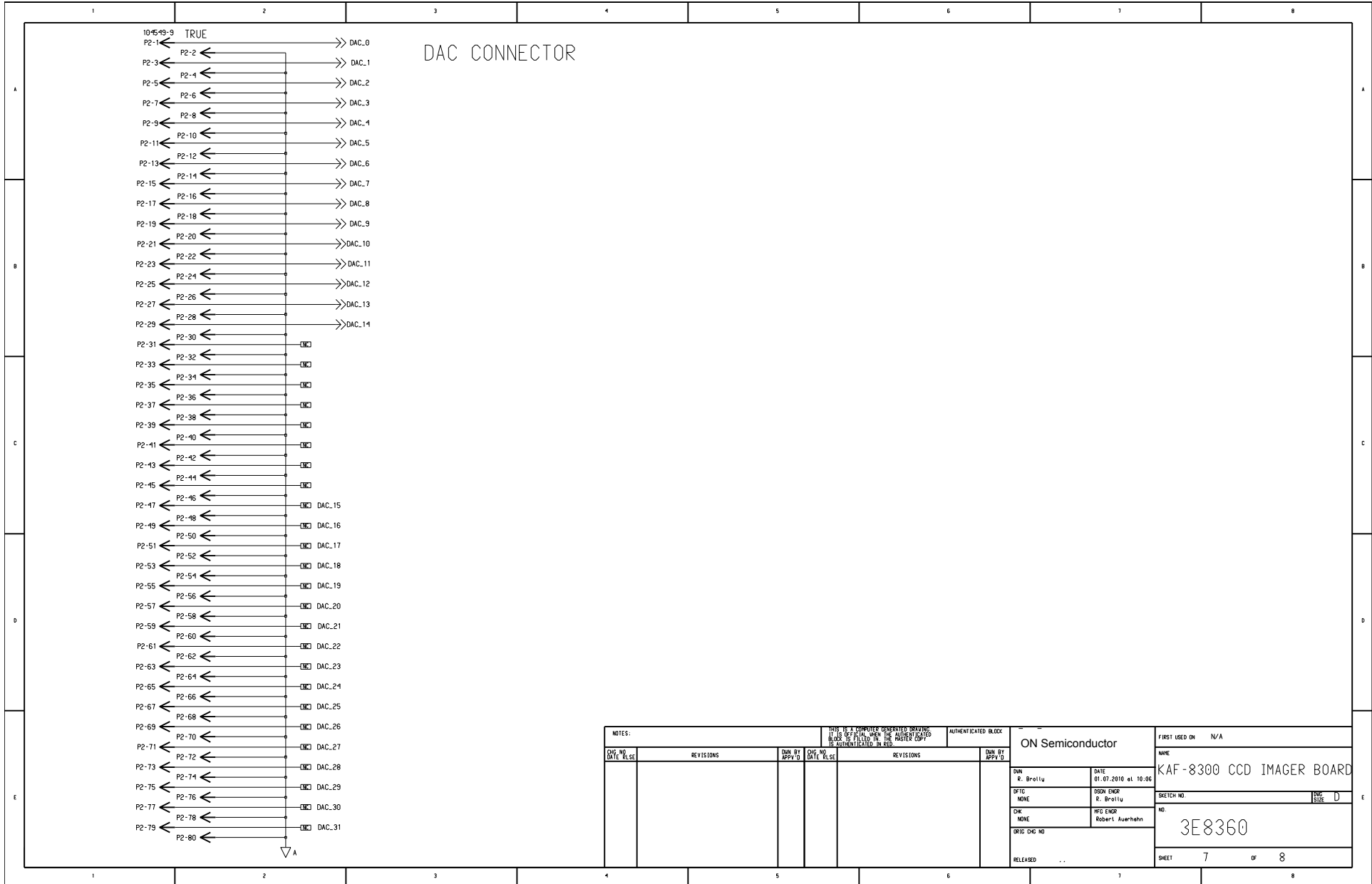




# V\_OUT

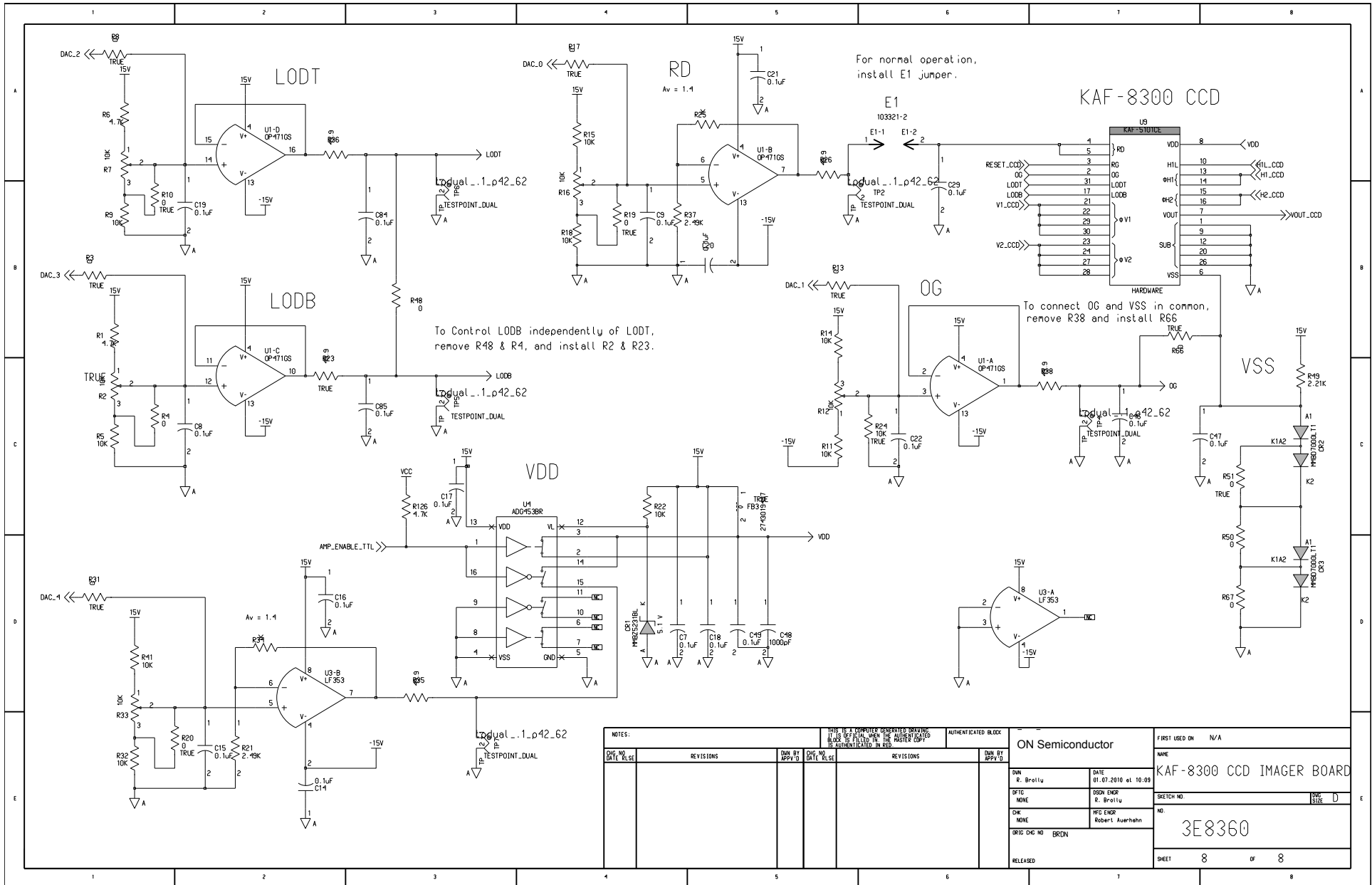


NOTES:		THIS IS A SUPPLIER GENERATED DRAWING. IT IS OF FINAL WHEN THE AUTHORIZED WORK IS PLACED IN THE PROPER COPY. IS AUTHORIZED TO RED.		AUTHENTICATED BLOCK	
CHG NO	DATE	REVISIONS	DATE	REVISIONS	DATE
BY	BY	BY	BY	BY	BY
ON Semiconductor			FIRST USED ON N/A		
NAME			KAF-8300 CCD IMAGER BOARD		
DATE		DATE		DATE	
01.07.2010 at 10:06		01.07.2010 at 10:06		01.07.2010 at 10:06	
DESIGN ENGR		DESIGN ENGR		DESIGN ENGR	
R. Bröllu		R. Bröllu		R. Bröllu	
CHK		CHK		CHK	
NONE		NONE		NONE	
MFG ENGR		MFG ENGR		MFG ENGR	
Robert Auerhahn		Robert Auerhahn		Robert Auerhahn	
PART NO			3E8360		
RELEASED			SHEET 6 OF 8		



DAC CONNECTOR

NOTES:		THIS IS A COMPUTER GENERATED DRAWING. IT IS NOT FINAL, WHEN THE AUTHORIZED WORK IS FILED IN THE MASTER COPY.		AUTHENTICATED BLOCK		FIRST USED ON N/A	
CHG. NO. DATE	REVISIONS	OWN BY APP'D	CHG. NO. DATE	REVISIONS	OWN BY APP'D	NAME KAF-8300 CCD IMAGER BOARD	
						DATE 01.07.2010 at 10:06	SKETCH NO.
						DESIGN ENGR R. Bröllu	SIZE D
						DRG ENGR Robert Auerhahn	NO. 3E8360
						RELEASED	SHEET 7 OF 8



DATE		REV		DATE		REV	
DATE	REV	DATE	REV	DATE	REV	DATE	REV

<b>ON Semiconductor</b> DWN R. Brölli DATE 01.07.2010 at 10:09 DFC NONE DSN ENGR R. Brölli CHK NONE HFG ENGR Robert Auerhahn BRD CHG NO BRDN RELEASED		FIRST USED ON N/A NAME <b>KAF-8300 CCD IMAGER BOARD</b> SKETCH NO. NO. <b>3E8360</b> SHEET 8 of 8
---	--	---



Components  
For Circuit Board Assembly

NO. **3E8360**  
SHEET 1 NEXT SHEET 2

Item No	Part no	Assy. Side	Item Reference Designators	Qty	Package style	Notes/Comp Description	CHG. NO DATE	REVISIONS	DR. BY APPS.
1	3E8359	HW-T-1	BRD1	1		BARE BOARD REV A			
2	335666	TOP-4	C1 C6 C23 C28	4	case_a_h.075	4.7uF_10V_.20 ELECTROLYTIC, TANTALUM CHIP	REV A	PRELIMINARY RELEASE	BPF
3	785076	BOT-5	C106 C122 C130 C131 C132	5	case_a_h.075	1uF_25V_.20 ELECTROLYTIC, TANTALUM	REV 1	INITIAL RELEASE	BPF
4	770251	TOP-2	C116 C134	2	case_d_h.130	10uF_35V_.10 ELECTROLYTIC, TANTALUM	REV 2	MODIFIED SH5	BPF
5	258541	TOP-8	C12 C93 C104 C121 C142 C143 C144 C145	8	case_c_h.110	10uF_20V_.20 ELECTROLYTIC TANTALUM CHIP	REV 3	UPDATED DOCUMENTATION	RBB
6	7B9655	TOP-1	C13	1	1206_h.060	1uF_16V_.20 MONOLITHIC, CERAMIC CHIP			
7	254471	TOP-12 BOT-14	C2 C4 C24 C26 C32 C52 C60 C70 C77 C88 C100 C119 C11 C48 C94 C108 C124 C127 C135 C136 C138 C140 C146 C147 C148 C149	26	0805_h.055	1000pF_50V_.05 MONOLITHIC, CERAMIC CHIP			
8	980646	BOT-7	C3 C5 C25 C27 C109 C125 C128	7	0805_h.055	0.01uF_50V_.10 MONOLITHIC, CERAMIC CHIP			
9	974989	TOP-1	C30	1	0805_h.055	0.1uF_25V_.10 MONOLITHIC, CERAMIC CHIP			
10	7E9452	BOT-1	C31	1	1206_h.070	2.2uF_10V_.10 MONOLITHIC CERAMIC CHIP			
11	4B3897	BOT-2	C33 C39	2	0805_h.055	33pF_50V_.05 CAPACITOR-CERAMIC MONOLITHIC CHIP (PF)			
12	954369	TOP-4 BOT-3	C35 C54 C55 C71 C50 C51 C69	7	case_a_h.075	2.2uF_16V_.20 ELECTROLYTIC TANTALUM CHIP			
13	8B0987	TOP-2	C44 C66	10	case_c_h.110	22uF_20V_.20 ELECTROLYTIC TANTALUM			

Notes: 1. REFER TO CIRCUIT DIAGRAM 3E8360

SEE SHEET		FOR ADD'L REVISIONS	
<b>ON Semiconductor</b>		FIRST USED ON	
DR. XXXX		NAME CIRCUIT BOARD ASSEMBLY	
DATE		KAF8300 CCD IMAGER BOARD	
DES. ENG.	PKG. MATL.	SKETCH NO.	DWG. SIZE B
CK. BPF DFTG. ENG.	MFG. ENG.	<b>3E8360</b>	
ORIG. CHG. NO. RELEASED	SHEET 1 NEXT SHEET 2		

Components  
For Circuit Board Assembly

NO. **3E8360**  
SHEET 2 NEXT SHEET 3

Item No	Part no	Assy. Side	Item Reference Designators	Qty	Package style	Notes/Comp Description	CHG. NO DATE	REVISIONS	DR. BY APPS.
		B0T-8	C78 C80 C87 C92 C99 C101 C113 C117			CHIP			
14	2B1595	B0T-6	C61 C62 C79 C89 C111 C112	6	0805_h.055	100pF_100V_.10 CAPACITOR-CERAMIC MONOLITHIC-CHIP (PF)	REV A	PRELIMINARY RELEASE	BPF
15	4B4495	TOP-1 B0T-3	C75 C37 C43 C82	4	case_b_h.085	4.7uF_20V_.20 ELECTROLYTIC TANTALUM CHIP	REV 1	INITIAL RELEASE	BPF
16	7B9716	TOP-20  B0T-45	C8 C9 C10 C15 C19 C22 C46 C47 C57 C59 C65 C68 C76 C84 C85 C86 C96 C97 C98 C118 C7 C14 C16 C17 C18 C20 C21 C29 C34 C36 C38 C40 C41 C42 C45 C49 C53 C56 C58 C63 C64 C67 C72 C73 C74 C81 C83 C90 C91 C95 C102 C103 C105 C107 C110 C114 C115 C120 C123 C126 C129 C133 C137 C139 C141	65	0805_h.055	0.1uF_50V_.10 Ceramic Monolithic Chip	REV 2	MODIFIED SH5	BPF
							REV 3	UPDATED DOCUMENTATION	RBB
17	254359	TOP-1	CR1	1	sot23_akn_sp	MMBZ5231BL DIODE, ZENER, 5.1V, 225mW			
18	586506	TOP-2	CR2 CR3	2	sot23_akak_s	MMBD7000LT1 DIODE, SWITCHING, DUAL, SERIES, 100V, 100mA			
19	902510	TOP-4	CR4 CR5 CR6 CR7	4	sot143_kkaa_	HSMS-2805 DIODE, SCHOTTKY BARRIER, DUAL, 70V, 15mA			
20	7E7515	TOP-1	E1	1	p02s_103321-	103321-2 STRAIGHT HEADER CONNECTOR			
21	233152	TOP-15	FB1 FB2 FB4 FB5 FB6 FB7 FB8 FB9 FB10 FB11 FB12 FB13 FB14 FB15 FB16	15	fb_274301944	2743019447 - FERRITE, SMT BEADS			
22	911244	TOP-1	J1	1	j01ra_221014	221014-1 SMB, R/A RF COAXIAL JACK, 75 OHM			

Notes: 1. REFER TO CIRCUIT DIAGRAM 3E8360

SEE SHEET		FOR ADD'L REVISIONS	
ON Semiconductor		FIRST USED ON	
		NAME CIRCUIT BOARD ASSEMBLY	
DR. XXXX	DATE	KAF8300 CCD IMAGER BOARD	
DES. ENG.	PKG. MATL.	SKETCH NO.	DWG. SIZE B
CK. BPF DFTG.	MFG. ENG.	3E8360	
ORIG. CHG. NO. RELEASED			
		SHEET 2	NEXT SHEET 3

Components  
For Circuit Board Assembly

NO. **3E8360**  
SHEET 3 NEXT SHEET 4

Item No	Part no	Assy. Side	Item Reference Designators	Qty	Package style	Notes/Comp Description	CHG. NO DATE	REVISIONS	DR. BY APPS.
23	1E1112	B0T-3	L1 L2 L3	3	ind_1008cs_h	2.2uH SMT WIREWOUND ENCAPSULATED			
24	999979	TOP-1	P1	1	p80s_104549-	104549-9 SMT, AMPMODU, SHROUDED HEADER CONNECTOR	REV A	PRELIMINARY RELEASE	BPF
25	616292	TOP-1	Q1	1	sot23_bce_sp	MMBT3904LT1 TRANSISTOR, NPN, 40V, GENERAL PURPOSE	REV 1	INITIAL RELEASE	BPF
26	233838	TOP-2	Q14 Q15	2	sot23_bce_sp	MMBT3906 TRANSISTOR, PNP, 40V, GENERAL PURPOSE	REV 2	MODIFIED SH5	BPF
27	4B4317	TOP-4	Q2 Q5 Q8 Q17	4	sot23_bce_sp	MMBT2369ALT1 TRANSISTOR, NPN, 15V, SWITCHING	REV 3	UPDATED DOCUMENTATION	RBB
28	236307	TOP-4	Q3 Q7 Q11 Q19	4	sot23_bce_sp	MMBT3640 TRANSISTOR, PNP, 12V, SWITCHING			
29	960471	TOP-3	Q4 Q10 Q18	3	sot223_bce_s	PZT2907A TRANSISTOR, PNP, 60V, GENERAL PURPOSE			
30	960472	TOP-3	Q6 Q13 Q21	3	sot223_bce_s	PZT2222A TRANSISTOR, NPN, 40V, GENERAL PURPOSE			
31	253549	TOP-3	R1 R6 R126	3	0805_h.030	4.7K 0hms .100W .05 THICK METAL FILM			
32	253955	TOP-2 B0T-1	R100 R146 R120	3	0805_h.030	20K 0hms .100W .05 FLAT, THICK METAL FILM, CHTP			
33	255504	TOP-2	R122 R124	2	0805_h.030	7.5K 0hms .100W .01 FLAT, THICK METAL FILM, CHIP			
34	783957	B0T-3	R140 R142 R151	3	0805_h.030	200 0hms .100W .01 FLAT, THICK METAL FILM, CHTP			
35	902942	TOP-1 B0T-1	R21 R37	2	0805_h.030	2.49K 0hms .100W .01 SMT CHIP FLAT THICK METAL FILM			
36	901801	TOP-4	R26 R35 R36 R38	4	0805_h.030	49.9 0hms .100W .01 SMT CHIP FLAT THICK METAL FILM			
37	250796	TOP-3	R27 R65 R108	5	0805_h.030	1K 0hms .100W .05 FLAT, THICK			

Notes: 1. REFER TO CIRCUIT DIAGRAM 3E8360

SEE SHEET		FOR ADD'L REVISIONS	
<b>ON Semiconductor</b>		FIRST USED ON	
DR. XXXX		NAME CIRCUIT BOARD ASSEMBLY	
DATE		KAF8300 CCD IMAGER BOARD	
DES. ENG.	PKG. MATL.	SKETCH NO.	DWG. SIZE B
CK. BPF DFTG.	MFG. ENG.	<b>3E8360</b>	
ORIG. CHG. NO.	RELEASED	SHEET 3	NEXT SHEET 4

Components  
For Circuit Board Assembly

NO. **3E8360**  
SHEET 4 NEXT SHEET 5

Item No	Part no	Assy. Side	Item Reference Designators	Qty	Package style	Notes/Comp Description	CHG. NO DATE	REVISIONS	DR. BY APPS.
38	954554	TOP-1	R25 R34	1	0805_h.030	METAL FILM, CHIP 75 Ohms .100W .01 SMT CHIP FLAT THICK METAL FILM	REV A	PRELIMINARY RELEASE	BPF
39	941226	TOP-1	R30	1	0805_h.030	130 Ohms .100W .01 SMT CHIP FLAT THICK METAL FILM	REV 1	INITIAL RELEASE	BPF
40	739757	TOP-1	R39	1	0805_h.030	680 Ohms .250W .05 FLAT, THICK METAL FILM, CHIP	REV 2	MODIFIED SH5	BPF
41	257516	TOP-18	R40	1	1210_h.025	0.05 Ohms .100W - ZERO OHM CHIP JUMPER	REV 3	UPDATED DOCUMENTATION	RBB
42	901770	TOP-18 BOT-4	R42 R48 R50 R53 R67 R68 R75 R79 R89 R90 R101 R102 R107 R111 R130 R131 R133 R134 R4 R61 R116 R138	22	0805_h.030				
43	233981	TOP-10 BOT-10	R49 R43 R56 R70 R96 R103 R112 R127 R141 R143 R152	11	0805_h.030	2.21K Ohms .100W .01 FLAT, THICK METAL FILM, CHIP			
44	254478	TOP-12 BOT-3	R5 R9 R11 R14 R15 R18 R22 R28 R32 R41 R46 R91 R59 R123 R125	15	0805_h.025	10K Ohms .100W .01 FLAT, THICK METAL FILM CHIP			
45	232841	TOP-4	R54 R95 R110 R132	4	0805_h.030	100K Ohms .100W .05 FLAT, THICK METAL FILM, CHIP			
46	255502	TOP-1	R55	1	0805_h.030	10 Ohms .100W .05 FLAT, THICK METAL FILM, CHIP			
47	255502	TOP-2 BOT-3	R62 R77 R88 R117 R137	5	0805_h.030	4.99K Ohms .100W .01 FLAT, THICK METAL FILM, CHIP			
48	902504	TOP-2 BOT-1	R64 R109 R29	3	0805_h.030	249 Ohms .100W .01 SMT CHIP FLAT THICK METAL FILM			
49	770026	TOP-14	R7 R12 R16 R33 R58 R63 R73 R87 R94 R98 R114 R121 R136 R145	14	pot_3266w_h.	10K POT, MULTI-TURN			

Notes: 1. REFER TO CIRCUIT DIAGRAM 3E8360

SEE SHEET		FOR ADD'L REVISIONS	
<b>ON Semiconductor</b>		FIRST USED ON	
DR. XXXX		NAME CIRCUIT BOARD ASSEMBLY	
DATE		KAF8300 CCD IMAGER BOARD	
DES. ENG.	PKG. MATL.	SKETCH NO.	DWG. SIZE B
CK. BPF DFTG. ENG.	MFG. ENG.	<b>3E8360</b>	
ORIG. CHG. NO. RELEASED	SHEET 4 NEXT SHEET 5		

Components  
For Circuit Board Assembly

NO. **3E8360**  
SHEET 5 NEXT SHEET 6

Item No	Part no	Assy. Side	Item Reference Designators	Qty	Package style	Notes/Comp Description	CHG. NO DATE	REVISIONS	DR. BY APPS.
49	980690	TOP-14	R81 R82 R104 R118 R128 R144 R147 R148 R149 R150 R153 R154 R155 R156	14	0805_h.030	100 Ohms .100W .005 SMT CHIP FLAT THIN METAL FILM	REV A	PRELIMINARY RELEASE	BPF
50	903960	TOP-3 BOT-4	R83 R84 R85 R44 R71 R72 R97	7	0805_h.030	3 Ohms .100W .05 FLAT, THICK METAL FILM, CHIP	REV 1	INITIAL RELEASE	BPF
51	901613	TOP-3	TP1 TP18 TP19	3	tp_tp104_h.2	TP-104-01-00 PRESS MOUNT TERMINAL - BLACK	REV 2	MODIFIED SH5	BPF
52	901614	TOP-4	TP13 TP15 TP16 TP17	4	tp_tp104_h.2	TP-104-01-02 PRESS MOUNT TERMINAL - RED	REV 3	UPDATED DOCUMENTATION	RBB
53	TPDUAL	TOP-12	TP2 TP3 TP4 TP5 TP6 TP7 TP8 TP9 TP10 TP11 TP12 TP14	12	tpdual_.1_p4	TP_DUAL DUAL TEST PADS (THRU HOLE)			
54	992863	TOP-1	U1	1	so116_.370_h	OP471 ANALOG IC, LINEAR AMPLIFIER,			
55	241054	TOP-1	U14	1	to220_aio_pd	LM337T 1.5A -40V -1.2 to -37V VOLTAGE REGULATOR, NEG ADJ, 1.5A,			
56	5E6841	TOP-1	U15	1	so120_.375_h	74AC540 BUFFER/DRIVER, OCTAL, W/ 3-STATE OUTPUT, INVERTING			
57	498310	TOP-1	U16	1	to220_aoi_pd	LM317T 1.5A 4.2-40V 1.2-37V VOLTAGE REGULATOR, ADJ, 1.5A, 3-TE			
58	691935	TOP-2	U17 U18	2	so16_.210_h.	DS90C032 DIFFERENTIAL LINE RECEIVER, QUAD			
59	5C2040	TOP-1	U2	1	so08_.210_h.	OPA642 WIDEBAND LOW DISTORTION OP AMP			
60	734408	TOP-4	U3 U8 U12 U13	4	so08_.210_h.	LF353 ANALOG IC, LINEAR AMPLIFIER,			
61	7E7954	TOP-1	U4	1	so16_.200_h.	ADG453BR ANALOG SWITCH, QUAD, SPST, 2 NC, 2 NO			

Notes: 1. REFER TO CIRCUIT DIAGRAM 3E8360

SEE SHEET		FOR ADD'L REVISIONS	
<b>ON Semiconductor</b>		FIRST USED ON	
		NAME CIRCUIT BOARD ASSEMBLY	
DR. XXXX	DATE	KAF8300 CCD IMAGER BOARD	
DES. ENG.	PKG. MATL.	SKETCH NO.	DWG. SIZE B
CK. BPF DFTG.	MFG. ENG.	<b>3E8360</b>	
ORIG. CHG. NO.	RELEASED	SHEET 5	NEXT SHEET 6

Components  
For Circuit Board Assembly

NO. **3E8360**  
SHEET 6 NEXT SHEET 7

Item No	Part no	Assy. Side	Item Reference Designators	Qty	Package style	Notes/Comp Description	CHG. NO DATE	REVISIONS	DR. BY APPS.
62	5C2045	TOP-1	U5	1	so08_.210_h.	DS1040 PULSE GENERATOR, PROGRAMMABLE ONE-SHOT	REV A	PRELIMINARY RELEASE	BPF
63	7E8545	TOP-2	U6 U10	2	so08_.200_h.	LM6172IM DUAL VOLTAGE FEEDBACK AMPLIFIER	REV 1	INITIAL RELEASE	BPF
64	4B4249	TOP-2	U7 U11	2	so08_.210_h.	MAX4427CSA DRIVER, DUAL, NON-INVERTING, 1.5A, MOSFET	REV 2	MODIFIED SH5	BPF
65	2H4928	BOT-1	U9	1	sensor_kof51	KAF-5101CE 2614x1966 FULL-FRAME CCD COLOR IMAGE SENSOR	REV 3	UPDATED DOCUMENTATION	RBB
66	7E7515	TOP-2	E2 E3	2NL	p02s_103321-	NO LOAD 103321-2 STRAIGHT HEADER CONNECTOR			
67	233152	TOP-1	FB3	1NL	fb_274301944	NO LOAD 2743019447 - FERRITE, SMT BEADS			
68	999979	TOP-1	P2	1NL	p80s_104549-	NO LOAD 104549-9 SMT, AMPMODU, SHROUDED HEADER CONNECTOR			
69	4B4317	TOP-2	Q9 Q16	2NL	sot23_bce_sp	NO LOAD MMBT2369ALT1 TRANSISTOR, NPN, 15V, SWITCHING			
70	236307	TOP-2	Q12 Q20	2NL	sot23_bce_sp	NO LOAD MMBT3640 TRANSISTOR, PNP, 12V, SWITCHING			
71	901801	TOP-1	R23	1NL	0805_h.030	NO LOAD 49.9 Ohms_.100W_.01 SMT CHIP FLAT THICK METAL FILM			
72	257516	TOP-19 BOT-4	R3 R8 R13 R17 R31 R47 R51 R52 R60 R66 R69 R76 R78 R92 R99 R105 R115 R129 R139 R10 R19 R20 R45	23NL	0805_h.030	NO LOAD 0.05 Ohms_.100W_- ZERO OHM CHIP JUMPER			
73	233981	BOT-10	R24 R57 R74 R80 R86 R93 R106 R113 R119 R135	10NL	0805_h.025	NO LOAD 10K Ohms_.100W_.01 FLAT, THICK METAL FILM CHIP			
74	770026	TOP-1	R2	1NL	pot_3266w_h.	NO LOAD 10K POT, MULTI-TURN			

Notes: 1. REFER TO CIRCUIT DIAGRAM 3E8360 -----

SEE SHEET		FOR ADD'L REVISIONS	
<b>ON Semiconductor</b>		FIRST USED ON	
		NAME CIRCUIT BOARD ASSEMBLY	
DR. XXXX	DATE	KAF8300 CCD IMAGER BOARD	
DES. ENG.	PKG. MATL.	SKETCH NO.	DWG. SIZE B
CK. BPF DFTG.	MFG. ENG.	<b>3E8360</b>	
ORIG. CHG. NO. RELEASED		SHEET 6	NEXT SHEET 7

Components  
For Circuit Board Assembly

NO. 3E8360

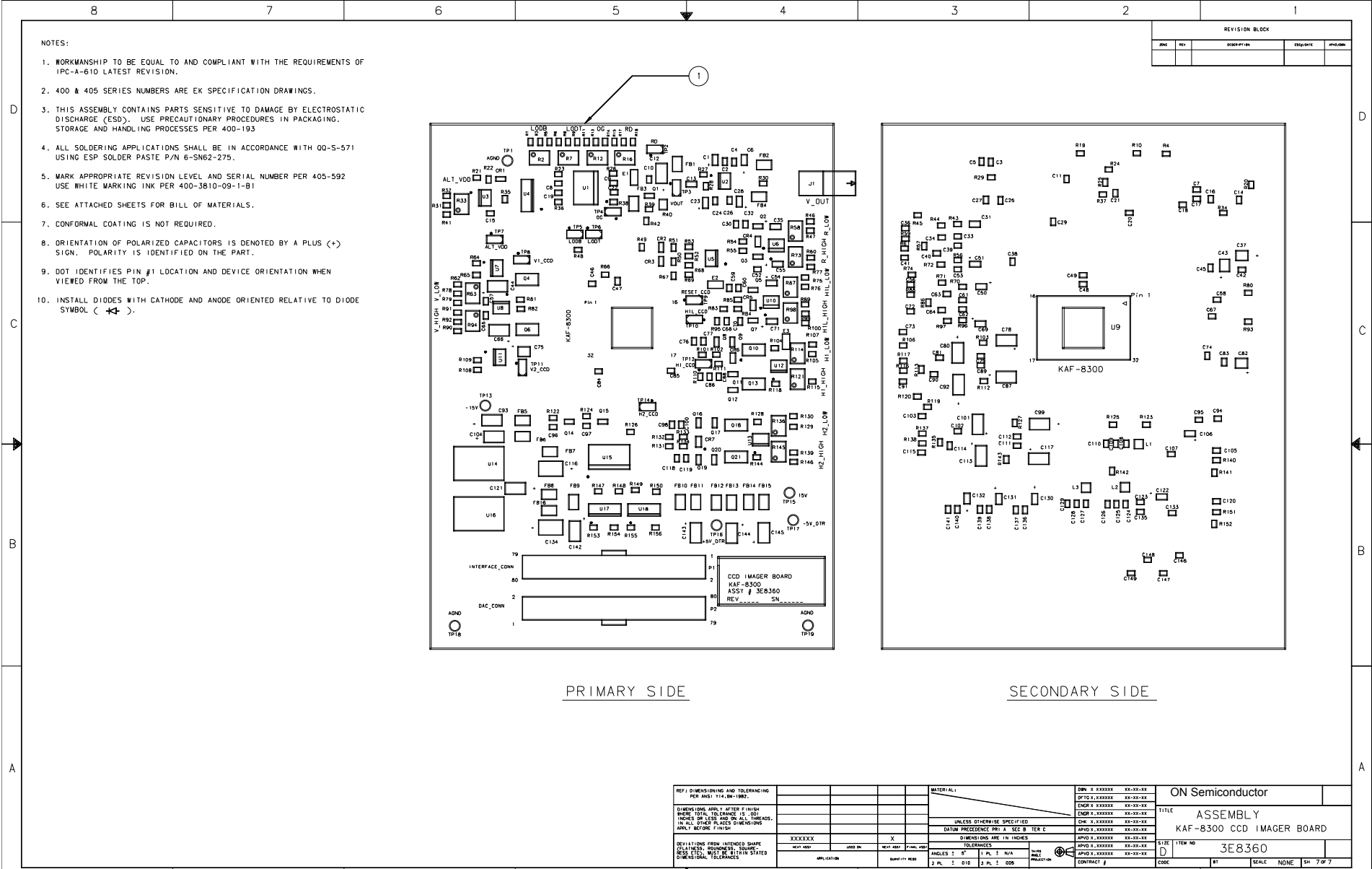
SHEET 7

NEXT SHEET 8

Item No	Part no	Assy. Side	Item Reference Designators	Qty	Package style	Notes/Comp Description	CHG. NO DATE	REVISIONS	DR. BY APPS.
75	5F1070	HW-B-32	XU9 XU9	32	HDWR	SOCKET For U9	REV A REV 1 REV 2 REV 3	PRELIMINARY RELEASE INITIAL RELEASE MODIFIED SH5 UPDATED DOCUMENTATION	BPF BPF BPF RBB

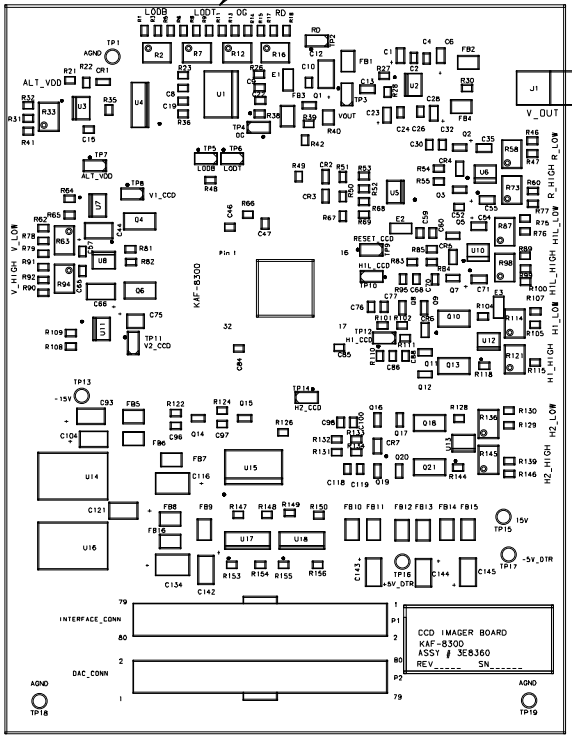
Notes: 1. REFER TO CIRCUIT DIAGRAM 3E8360 -----

SEE SHEET		FOR ADD'L REVISIONS	
<b>ON Semiconductor</b>		FIRST USED ON	
DR. XXXX		NAME CIRCUIT BOARD ASSEMBLY	
DATE		KAF8300 CCD IMAGER BOARD	
DES. ENG.	PKG. MATL.	SKETCH NO.	DWG. SIZE B
CK. RBB	MFG. ENG.	3E8360	
DFTG.	ENG.		
ORIG. CHG. NO.	RELEASED	SHEET 7	NEXT SHEET 8

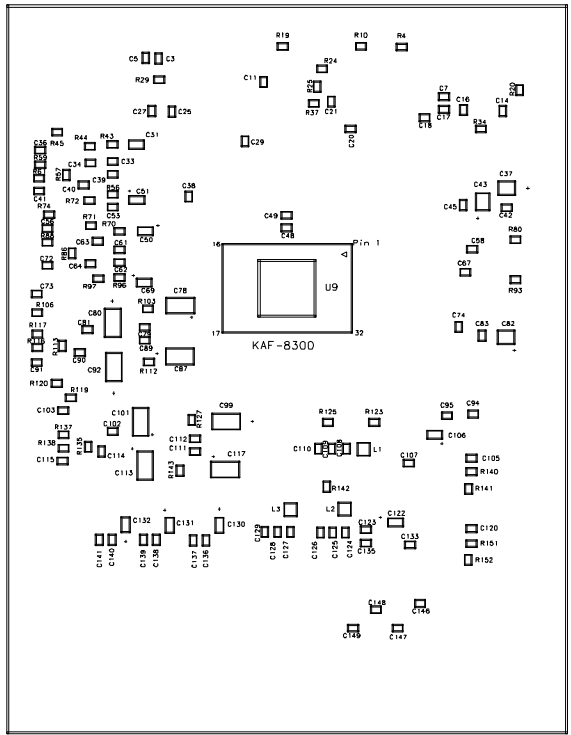


- NOTES:
- WORKMANSHIP TO BE EQUAL TO AND COMPLIANT WITH THE REQUIREMENTS OF IPC-A-610 LATEST REVISION.
  - 400 & 405 SERIES NUMBERS ARE EK SPECIFICATION DRAWINGS.
  - THIS ASSEMBLY CONTAINS PARTS SENSITIVE TO DAMAGE BY ELECTROSTATIC DISCHARGE (ESD). USE PRECAUTIONARY PROCEDURES IN PACKAGING, STORAGE AND HANDLING PROCESSES PER 400-193
  - ALL SOLDERING APPLICATIONS SHALL BE IN ACCORDANCE WITH 00-5-571 USING ESP SOLDER PASTE P/N 6-SN62-275.
  - MARK APPROPRIATE REVISION LEVEL AND SERIAL NUMBER PER 405-592 USE WHITE MARKING INK PER 400-3810-09-1-B1
  - SEE ATTACHED SHEETS FOR BILL OF MATERIALS.
  - CONFORMAL COATING IS NOT REQUIRED.
  - ORIENTATION OF POLARIZED CAPACITORS IS DENOTED BY A PLUS (+) SIGN. POLARITY IS IDENTIFIED ON THE PART.
  - DOT IDENTIFIES PIN #1 LOCATION AND DEVICE ORIENTATION WHEN VIEWED FROM THE TOP.
  - INSTALL DIODES WITH CATHODE AND ANODE ORIENTED RELATIVE TO DIODE SYMBOL (<math>\leftarrow</math>).

REVISION BLOCK				
REV	REV	DESCRIPTION	DATE	APPROVED



PRIMARY SIDE



SECONDARY SIDE

REF. DIMENSIONING AND TOLERANCING PER ANSI Y14.1M-1982.		MATERIAL:		DIN X XXXXX XX-XX-XX		ON Semiconductor	
DIMENSIONS AND TOLERANCES UNLESS OTHERWISE SPECIFIED ARE IN INCHES.		UNLESS OTHERWISE SPECIFIED		DIN X XXXXX XX-XX-XX		TITLE	
DIMENSIONS AND TOLERANCES UNLESS OTHERWISE SPECIFIED ARE IN MILLIMETERS.		UNLESS OTHERWISE SPECIFIED		DIN X XXXXX XX-XX-XX		ASSEMBLY	
DIMENSIONS AND TOLERANCES UNLESS OTHERWISE SPECIFIED ARE IN MILLIMETERS.		UNLESS OTHERWISE SPECIFIED		DIN X XXXXX XX-XX-XX		KAF-8300 CCD IMAGER BOARD	
DIMENSIONS AND TOLERANCES UNLESS OTHERWISE SPECIFIED ARE IN MILLIMETERS.		UNLESS OTHERWISE SPECIFIED		DIN X XXXXX XX-XX-XX		ITEM NO	
DIMENSIONS AND TOLERANCES UNLESS OTHERWISE SPECIFIED ARE IN MILLIMETERS.		UNLESS OTHERWISE SPECIFIED		DIN X XXXXX XX-XX-XX		3E8360	
DIMENSIONS AND TOLERANCES UNLESS OTHERWISE SPECIFIED ARE IN MILLIMETERS.		UNLESS OTHERWISE SPECIFIED		DIN X XXXXX XX-XX-XX		SCALE NONE	
DIMENSIONS AND TOLERANCES UNLESS OTHERWISE SPECIFIED ARE IN MILLIMETERS.		UNLESS OTHERWISE SPECIFIED		DIN X XXXXX XX-XX-XX		SH 7 OF 7	